



# AO4455

## 30V P-Channel MOSFET

### General Description

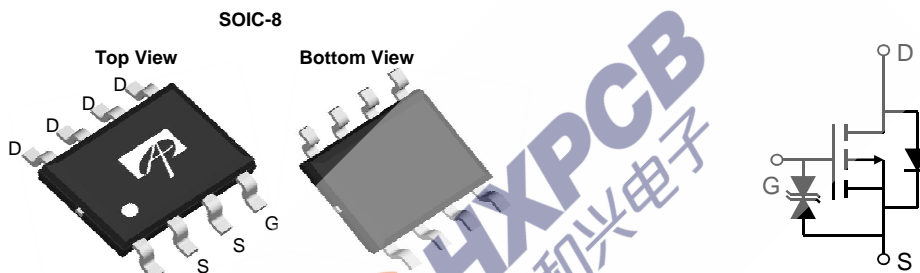
The AO4455 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , and ultra-low gate charge with a 25V gate rating. This device is suitable for use as a load switch or in PWM applications.

\* RoHS and Halogen-Free Compliant

### Product Summary

$V_{DS}$  (V) = -30V  
 $I_D$  = -17A ( $V_{GS} = -20V$ )  
 $R_{DS(ON)} < 6.2m\Omega$  ( $V_{GS} = -20V$ )  
 $R_{DS(ON)} < 7.2m\Omega$  ( $V_{GS} = -10V$ )

ESD Protected  
 100% UIS tested  
 100% Rg tested



### Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

| Parameter                              | Symbol         | Maximum          | Units      |
|--|----------------|------------------|------------|
| Drain-Source Voltage                   | $V_{DS}$       | -30              | V          |
| Gate-Source Voltage                    | $V_{GS}$       | $\pm 25$         | V          |
| Continuous Drain Current <sup>AF</sup> | $I_D$          | $T_A=25^\circ C$ | -17        |
|  |                | $T_A=70^\circ C$ | -14        |
| Pulsed Drain Current <sup>B</sup>      | $I_{DM}$       | -182             | A          |
| Power Dissipation <sup>A</sup>         | $P_D$          | $T_A=25^\circ C$ | 3.1        |
|  |                | $T_A=70^\circ C$ | 2          |
| Junction and Storage Temperature Range | $T_J, T_{STG}$ | -55 to 150       | $^\circ C$ |

### Thermal Characteristics

| Parameter                                 | Symbol          | Typ          | Max | Units        |
|---|-----------------|--------------|-----|--------------|
| Maximum Junction-to-Ambient <sup>AF</sup> | $R_{\theta JA}$ | $t \leq 10s$ | 26  | $^\circ C/W$ |
| Maximum Junction-to-Ambient <sup>A</sup>  |                 | Steady-State | 50  | $^\circ C/W$ |
| Maximum Junction-to-Lead <sup>C</sup>     | $R_{\theta JL}$ | 14           | 24  | $^\circ C/W$ |

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

| Symbol                      | Parameter                             | Conditions   | Min  | Typ      | Max      | Units |
|-----------------------------|---------------------------------------|--|------|----------|----------|-------|
| <b>STATIC PARAMETERS</b>    |                                       |  |      |          |          |       |
| BV <sub>DSS</sub>           | Drain-Source Breakdown Voltage        | I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V                          | -30  |          |          | V     |
| I <sub>DSS</sub>            | Zero Gate Voltage Drain Current       | V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V<br>T <sub>J</sub> =55°C   |      |          | -1<br>-5 | μA    |
| I <sub>GSS</sub>            | Gate-Body leakage current             | V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V                           |      |          | ±1       | μA    |
|                             |                                       | V <sub>DS</sub> =0V, V <sub>GS</sub> =±25V                           |      |          | ±10      | μA    |
| V <sub>GS(th)</sub>         | Gate Threshold Voltage                | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA            | -1.5 | -2.1     | -2.6     | V     |
| R <sub>DS(ON)</sub>         | Static Drain-Source On-Resistance     | V <sub>GS</sub> =-20V, I <sub>D</sub> =-15A<br>T <sub>J</sub> =125°C |      | 5<br>7.2 | 6.2<br>9 | mΩ    |
|                             |                                       | V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A                          |      | 5.7      | 7.2      | mΩ    |
|                             |                                       | V <sub>GS</sub> =-6V, I <sub>D</sub> =-10A                           |      | 7.4      | 9.5      | mΩ    |
| g <sub>FS</sub>             | Forward Transconductance              | V <sub>DS</sub> =-5V, I <sub>D</sub> =-15A                           |      | 48       |          | S     |
| V <sub>SD</sub>             | Diode Forward Voltage                 | I <sub>S</sub> =-1A, V <sub>GS</sub> =0V                             |      | -0.7     | -1       | V     |
| I <sub>S</sub>              | Maximum Body-Diode Continuous Current |  |      |          | -4.2     | A     |
| <b>DYNAMIC PARAMETERS</b>   |                                       |  |      |          |          |       |
| C <sub>iss</sub>            | Input Capacitance                     |  |      | 2823     | 3400     | pF    |
| C <sub>oss</sub>            | Output Capacitance                    | V <sub>GS</sub> =0V, V <sub>DS</sub> =-15V, f=1MHz                   |      | 574      |          | pF    |
| C <sub>riss</sub>           | Reverse Transfer Capacitance          |  |      | 424      | 600      | pF    |
| R <sub>g</sub>              | Gate resistance                       | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz                     | 2.1  | 4.0      | 6.4      | Ω     |
| <b>SWITCHING PARAMETERS</b> |                                       |  |      |          |          |       |
| Q <sub>g</sub>              | Total Gate Charge                     |  |      | 54       | 76       | nC    |
| Q <sub>gs</sub>             | Gate Source Charge                    | V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, I <sub>D</sub> =-15A   |      | 9        |          | nC    |
| Q <sub>gd</sub>             | Gate Drain Charge                     |  |      | 16       |          | nC    |
| t <sub>D(on)</sub>          | Turn-On Delay Time                    |  |      | 12.5     |          | ns    |
| t <sub>r</sub>              | Turn-On Rise Time                     | V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>L</sub> =1.0Ω,  |      | 12.5     |          | ns    |
| t <sub>D(off)</sub>         | Turn-Off Delay Time                   | R <sub>GEN</sub> =3Ω   |      | 49       |          | ns    |
| t <sub>f</sub>              | Turn-Off Fall Time                    |  |      | 109      |          | ns    |
| t <sub>rr</sub>             | Body Diode Reverse Recovery Time      | I <sub>F</sub> =-15A, di/dt=100A/μs                                  |      | 22.3     | 32       | ns    |
| Q <sub>rr</sub>             | Body Diode Reverse Recovery Charge    | I <sub>F</sub> =-15A, di/dt=100A/μs                                  |      | 8.8      |          | nC    |

A: The value of R<sub>θJA</sub> is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to lead R<sub>θJL</sub> and lead to ambient.

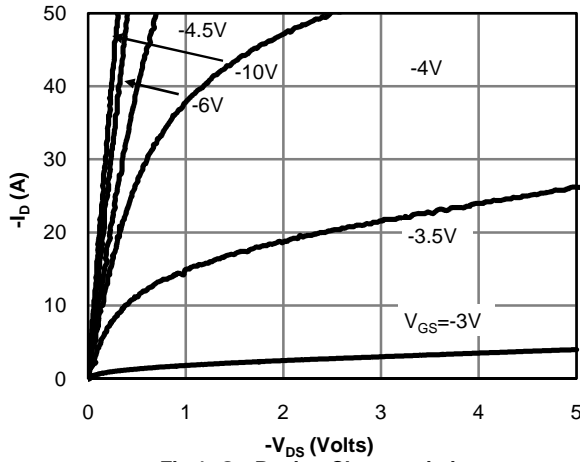
D: The static characteristics in Figures 1 to 6 are obtained using <300 μs pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25° C. The SOA curve provides a single pulse rating.

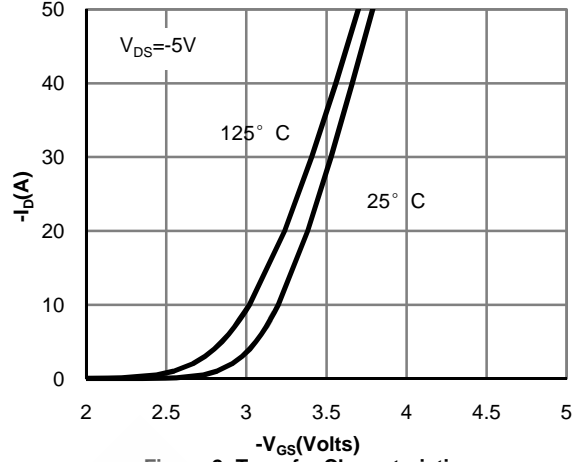
F: The current rating is based on the t ≤ 10s junction to ambient thermal resistance rating.

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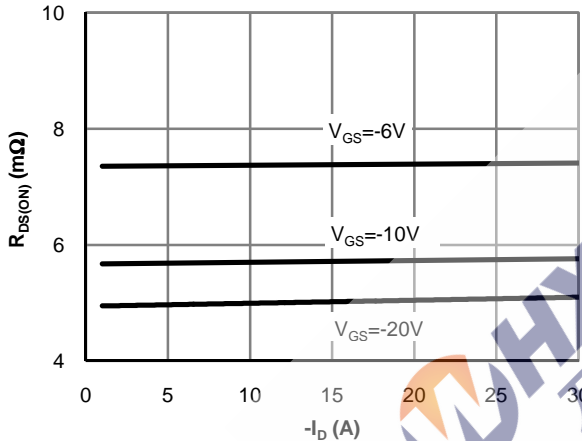
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**



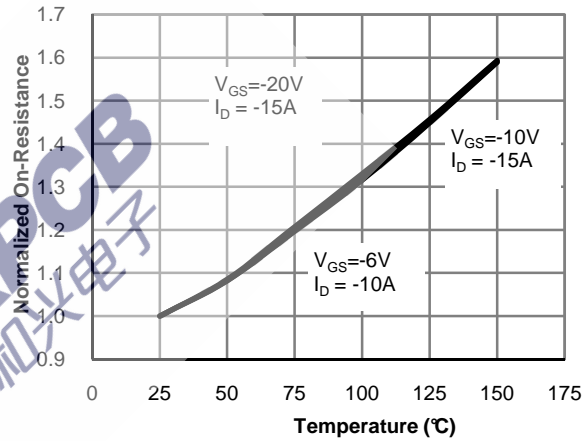
**Fig 1: On-Region Characteristics**



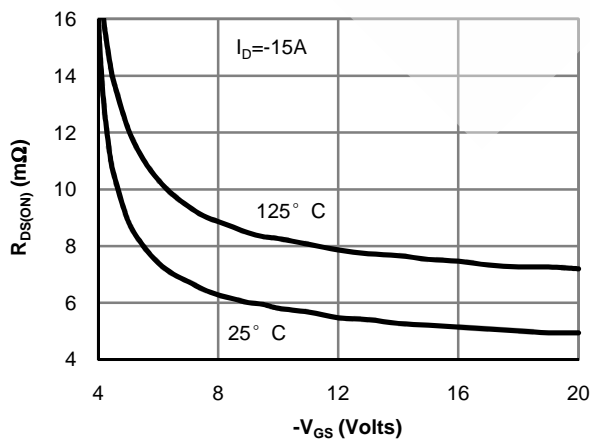
**Figure 2: Transfer Characteristics**



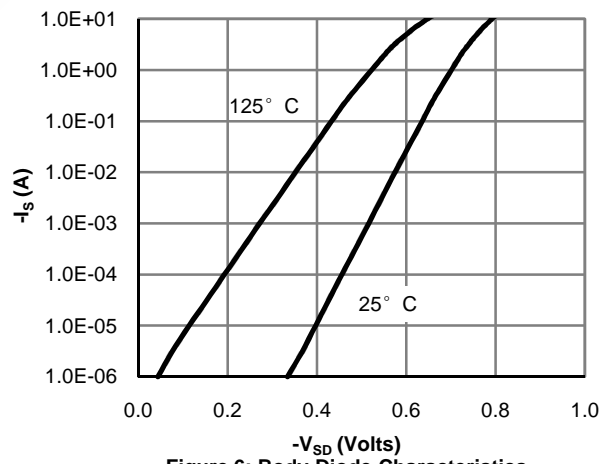
**Figure 3: On-Resistance vs. Drain Current and Gate Voltage**



**Figure 4: On-Resistance vs. Junction Temperature**



**Figure 5: On-Resistance vs. Gate-Source Voltage**



**Figure 6: Body-Diode Characteristics**

**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

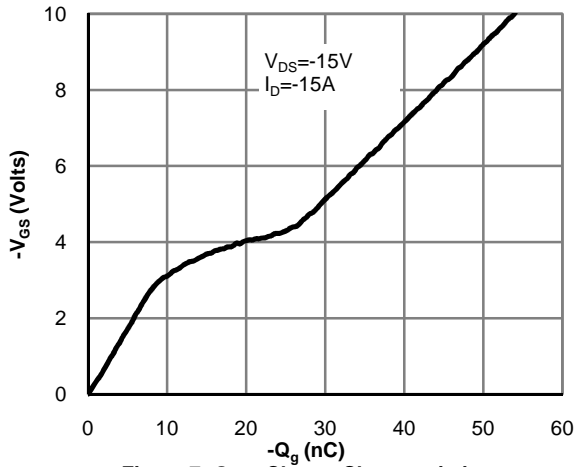


Figure 7: Gate-Charge Characteristics

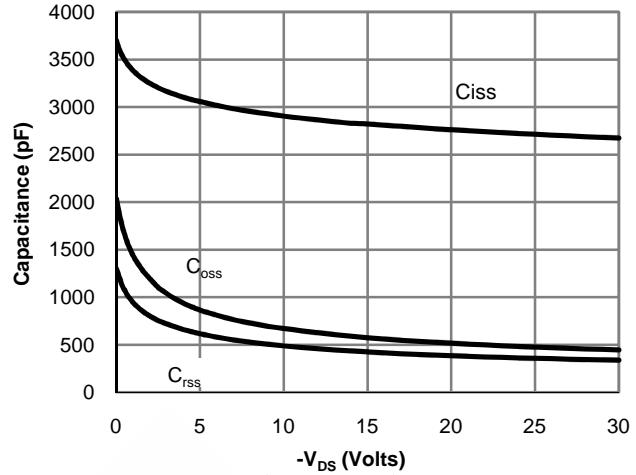


Figure 8: Capacitance Characteristics

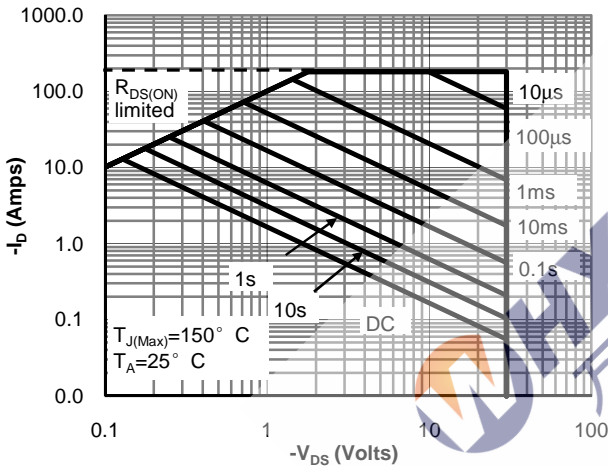


Figure 9: Maximum Forward Biased Safe

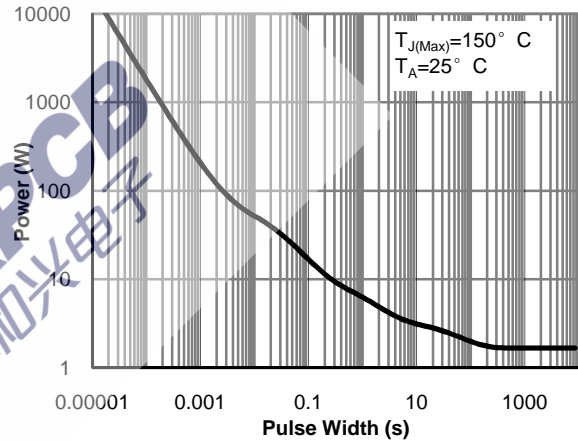


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

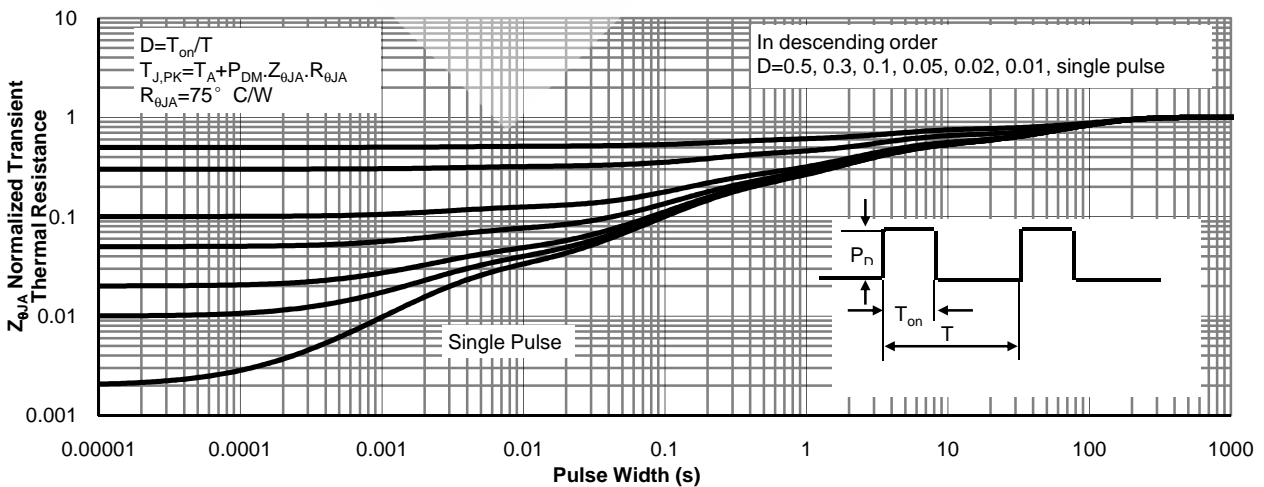
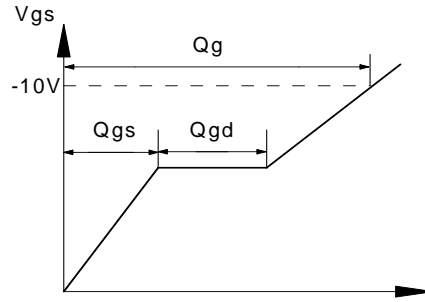
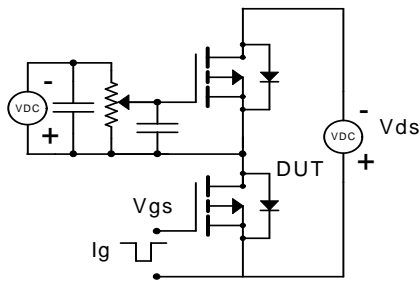
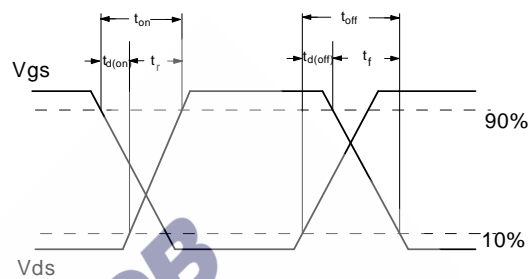
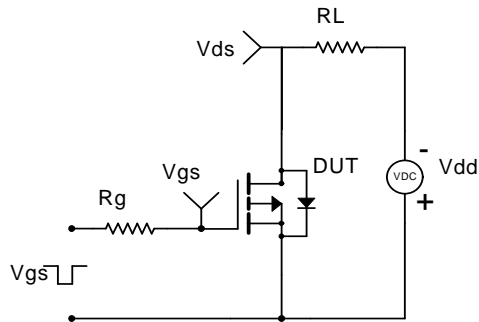


Figure 11: Normalized Maximum Transient Thermal Impedance

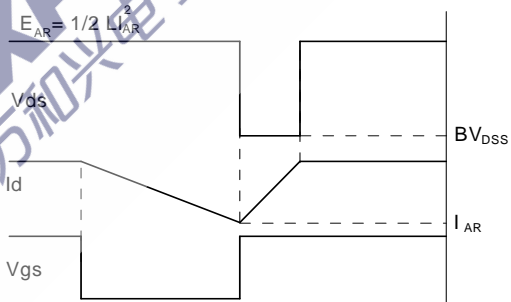
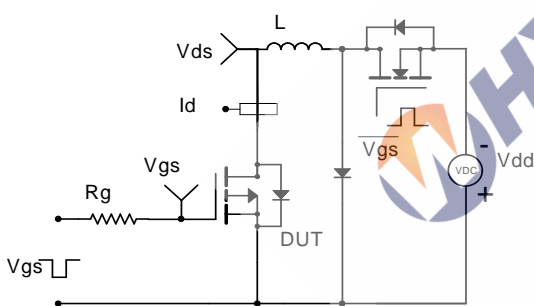
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

